





Serial No. 09/920,713  
IIZ.003D2  
Amendment dated October 16, 2003

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re PATENT APPLICATION of

Takashi Ohsumi

Group Art Unit: 2823

Serial No.: 09/920,713

Examiner: F. Toledo

Filed: August 3, 2001

For: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS  
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS

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**AMENDMENT UNDER 37 C.F.R. 1.116**

U.S. Patent and Trademark Office  
2011 South Clark Place  
Customer Window, **Mail Stop AF**  
Crystal Plaza Two, Lobby, Room 1B03  
Arlington, VA 22202

Date: October 16, 2003

Sir:

In response to the Final Office Action dated April 17, 2003, the period for response having been extended three (3) months to October 17, 2003, and further responsive to the Advisory Action dated October 3, 2003, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

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**Remarks/Arguments** begin on page 6 of this paper.